

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-8. (cancelled):

9. (currently amended):

A method for separating a silicon wafer, the method comprising:

coating a surface of the silicon wafer with a water soluble flux; ~~soluble protective coat;~~
and

laser scribing the coated surface of the silicon ~~wafer-~~wafer; and

saw cutting the silicon wafer under a flow of water at room temperature sufficient to remove at least a substantial portion of the water soluble flux.

10. (cancelled)

11. (original):

The method of claim 9 further comprising washing the silicon wafer with a solvent.

12.-13. (cancelled)

14. (currently amended):

The method of claim 9 wherein the silicon wafer includes die bumps and the coating includes coating the die bumps with the water soluble flux. ~~soluble protective coat.~~

15. (currently amended):

The method of claim 9 wherein the water soluble flux ~~soluble protective coat~~ is optically transparent.

16. (currently amended):

The method of claim 9 wherein the water soluble flux ~~soluble protective coat~~ is ablated by the laser scribing.

17.-19. (cancelled)

20. (currently amended):

A method for separating a silicon wafer, the method comprising:

laser scribing the silicon wafer having a soluble protective coat, wherein the soluble protective coat is ablated by the laser scribing;

saw cutting the silicon wafer after laser scribing; ~~having a soluble protective coat;~~ and providing a flow of water at room temperature ~~solvent~~ during the saw cutting, the flow of water ~~solvent~~ being sufficient to remove at least a substantial portion of the soluble protective coat.

21. (original):

The method of claim 20 wherein the soluble protective coat is one of a flux, a film, a tape, a polymer, and an organic solderability preservative.

22. (currently amended):

The method of claim 20 wherein the soluble protective coat is a water soluble flux. ~~flux and the solvent is water.~~

23. (cancelled)

24. (original):

The method of claim 20 wherein the silicon wafer includes die bumps and the soluble protective coat covers the die bumps.

25. (cancelled)

26. (original):

The method of claim 25 wherein the soluble protective coat is optically transparent.

27.-29. (cancelled)

30. (original):

The method of claim 20 wherein solvent is pressurized sufficiently to remove at least a substantial portion of the soluble protective coat.